

Thermosetting moulding compounds – Characteristics

	Thermal resistance	Dimensional stability	Mechanical strength	Electrical insulation	Tracking resistance	Chemical resistance	Hydrolysis resistance	Tribological behaviour	Crack resistance	Embedding of electrical inserts
EPOXIDUR® Epoxy resin moulding compounds	••	••	•••	•••	••	•••	•••	•••	•••	•••
MELOPAS® Melamine resin & melamine/phenolic resin moulding compounds				••	•••		•	••		
SILICONE resin moulding compounds	•••	••		••	••	•	••		•	•
RESINOL® Phenolic resin moulding compounds	••	•••	•••	•	•	••	•		•••	
RALUPOL® Unsaturated polyester resin moulding compounds	•	•	••	••	•••			•	••	•
AMPAL® Melamine/polyester resin moulding compounds			•	••	•••			•••	•	
DAP & DAIP Diallyl phthalate resin & diallyl iso-phthalate resin moulding compounds	•	•	•	••	••	•	••	•	•	••

This table is not intended to be exhaustive. Our experts will be pleased to help you select the optimal product for your application.

Should your search for a product for your application not be successful, please do not hesitate to contact us. If required, we offer the possibility to design an individualised and tailor-made product together with you.